

HSB88AS

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0586-0100 (Previous: ADE-208-964)

Rev.1.00

Mar 31, 2005

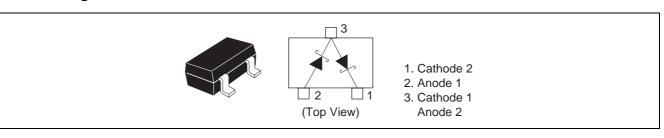
Features

- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB88AS	C1	CMPAK	PTSP0003ZB-A
			(CMPAK)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	lo *1	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	0.350	_	0.420	V	I _F = 1 mA
	V _{F2}	0.500	_	0.580		I _F = 10 mA
Reverse current	I _{R1}		_	0.2	μА	V _R = 2 V
	I _{R2}		_	10		V _R = 10 V
Capacitance	С	_	_	0.80	pF	V _R = 0 V, f = 1 MHz
Capacitance deviation	ΔC	_	_	0.10	pF	V _R = 0 V, f = 1 MHz
Forward voltage deviation	ΔV_{F}	_	_	10	mV	I _F = 10 mA
ESD-Capabilityme *2	_	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; $I_R > 0.4~\mu A$ at $V_R = 2V$

Main Characteristic

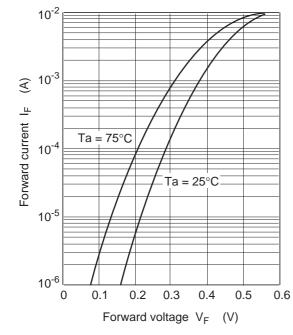


Fig.1 Forward current vs. Forward voltage

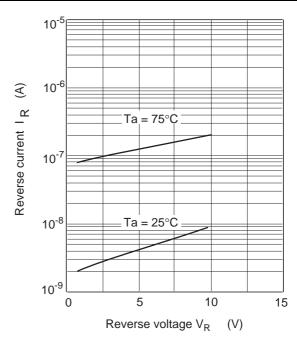
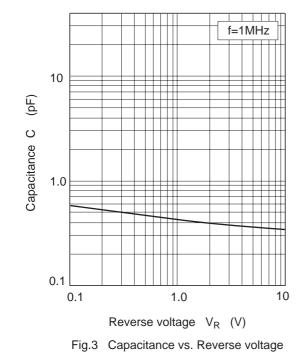
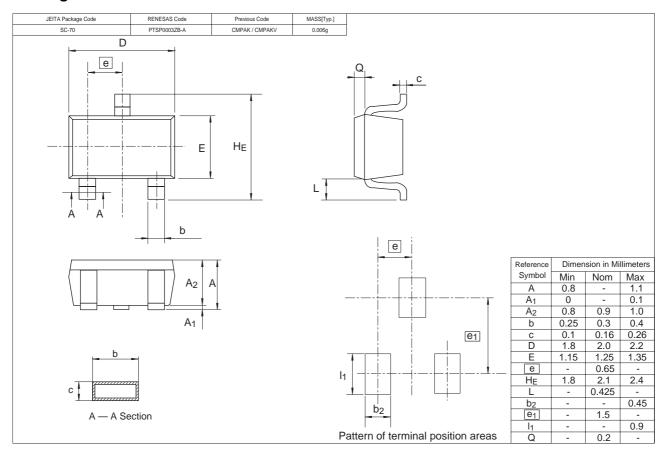


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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